



## Dual N-Channel 30 V (D-S) MOSFETs with Schottky Diode

PRODUCT SUMMARY				
	V <sub>DS</sub> (V)	R <sub>DS(on)</sub> (Ω)	I <sub>D</sub> (A)	Q <sub>g</sub> (Typ.)
Channel-1	30	0.0093 at V <sub>GS</sub> = 10 V	16 <sup>a</sup>	7.7 nC
		0.0130 at V <sub>GS</sub> = 4.5 V	16 <sup>a</sup>	
Channel-2	30	0.0047 at V <sub>GS</sub> = 10 V	35 <sup>a</sup>	17 nC
		0.0059 at V <sub>GS</sub> = 4.5 V	35 <sup>a</sup>	

### FEATURES

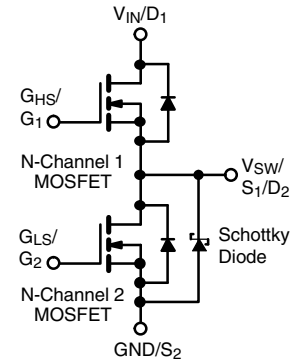
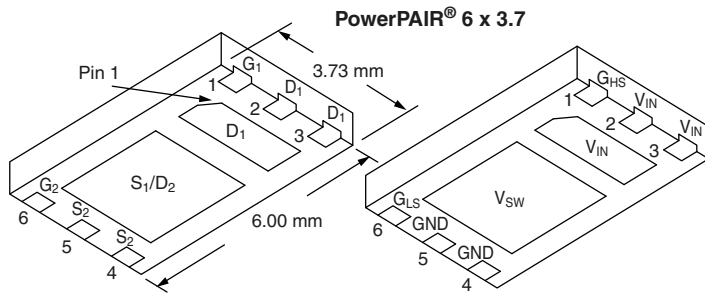
- Halogen-free According to IEC 61249-2-21 Definition
- SkyFET<sup>®</sup> Monolithic TrenchFET<sup>®</sup> Power MOSFETs and Schottky Diode
- 100 % R<sub>g</sub> Tested
- 100 % UIS Tested
- Compliant to RoHS Directive 2002/95/EC



RoHS  
COMPLIANT  
HALOGEN  
FREE

### APPLICATIONS

- System Power
  - Notebook
  - Server
- POL
- Synchronous Buck Converter



Ordering Information: SiZ790DT-T1-GE3 (Lead (Pb)-free and Halogen-free)

ABSOLUTE MAXIMUM RATINGS (T <sub>A</sub> = 25 °C, unless otherwise noted)					
Parameter	Symbol	Channel-1	Channel-2	Unit	
Drain-Source Voltage	V <sub>DS</sub>	30		V	
Gate-Source Voltage	V <sub>GS</sub>	± 20			
Continuous Drain Current (T <sub>J</sub> = 150 °C)	I <sub>D</sub>	T <sub>C</sub> = 25 °C	16 <sup>a</sup>	35 <sup>a</sup>	A
		T <sub>C</sub> = 70 °C	16 <sup>a</sup>	35 <sup>a</sup>	
		T <sub>A</sub> = 25 °C	12.9 <sup>b, c</sup>	23.4 <sup>b, c</sup>	
		T <sub>A</sub> = 70 °C	10.3 <sup>b, c</sup>	18.7 <sup>b, c</sup>	
Pulsed Drain Current (t = 300 μs)	I <sub>DM</sub>	70	100		
Continuous Source Drain Diode Current	I <sub>S</sub>	T <sub>C</sub> = 25 °C	16 <sup>a</sup>	35 <sup>a</sup>	
		T <sub>A</sub> = 25 °C	3.2 <sup>b, c</sup>	3.8 <sup>b, c</sup>	
Single Pulse Avalanche Current	I <sub>AS</sub>	16	30		
Single Pulse Avalanche Energy	E <sub>AS</sub>	13	45	mJ	
Maximum Power Dissipation	P <sub>D</sub>	T <sub>C</sub> = 25 °C	27	48	W
		T <sub>C</sub> = 70 °C	17	31	
		T <sub>A</sub> = 25 °C	3.9 <sup>b, c</sup>	4.6 <sup>b, c</sup>	
		T <sub>A</sub> = 70 °C	2.5 <sup>b, c</sup>	3 <sup>b, c</sup>	
Operating Junction and Storage Temperature Range	T <sub>J</sub> , T <sub>stg</sub>	- 55 to 150		°C	
Soldering Recommendations (Peak Temperature) <sup>d, e</sup>		260			

THERMAL RESISTANCE RATINGS							
Parameter	Symbol	Channel-1		Channel-2		Unit	
		Typ.	Max.	Typ.	Max.		
Maximum Junction-to-Ambient <sup>b, f</sup>	R <sub>thJA</sub>	24	32	20	27	°C/W	
Maximum Junction-to-Case (Drain)	R <sub>thJC</sub>	3.5	4.6	2	2.6		

Notes:

- Package limited.
- Surface mounted on 1" x 1" FR4 board.
- t = 10 s.
- See solder profile ([www.vishay.com/ppg?73257](http://www.vishay.com/ppg?73257)). The PowerPAIR is a leadless package. The end of the lead terminal is exposed copper (not plated) as a result of the singulation process in manufacturing. A solder fillet at the exposed copper tip cannot be guaranteed and is not required to ensure adequate bottom side solder interconnection.
- Rework conditions: manual soldering with a soldering iron is not recommended for leadless components.
- Maximum under steady state conditions is 67 °C/W for channel-1 and 65 °C/W for channel-2.

SPECIFICATIONS ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Static</b>							
Drain-Source Breakdown Voltage	$V_{DS}$	$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	Ch-1	30		V	
		$V_{GS} = 0\text{ V}, I_D = 250\text{ }\mu\text{A}$	Ch-2	30			
Gate Threshold Voltage	$V_{GS(th)}$	$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	Ch-1	1	2.2		
		$V_{DS} = V_{GS}, I_D = 250\text{ }\mu\text{A}$	Ch-2	1.1	2.2		
Gate Source Leakage	$I_{GSS}$	$V_{DS} = 0\text{ V}, V_{GS} = \pm 20\text{ V}$	Ch-1		$\pm 100$	nA	
			Ch-2		$\pm 100$		
Zero Gate Voltage Drain Current	$I_{DSS}$	$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	Ch-1		1	$\mu\text{A}$	
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}$	Ch-2		50		
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$	Ch-1		5		
		$V_{DS} = 30\text{ V}, V_{GS} = 0\text{ V}, T_J = 55\text{ }^\circ\text{C}$	Ch-2		140		1400
On-State Drain Current <sup>b</sup>	$I_{D(on)}$	$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	Ch-1	15		A	
		$V_{DS} \geq 5\text{ V}, V_{GS} = 10\text{ V}$	Ch-2	20			
Drain-Source On-State Resistance <sup>b</sup>	$R_{DS(on)}$	$V_{GS} = 10\text{ V}, I_D = 15\text{ A}$	Ch-1		0.0075	0.0093	$\Omega$
		$V_{GS} = 10\text{ V}, I_D = 20\text{ A}$	Ch-2		0.0038	0.0047	
		$V_{GS} = 4.5\text{ V}, I_D = 13\text{ A}$	Ch-1		0.0105	0.0130	
		$V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$	Ch-2		0.0048	0.0059	
Forward Transconductance <sup>b</sup>	$g_{fs}$	$V_{DS} = 15\text{ V}, I_D = 15\text{ A}$	Ch-1		48	S	
		$V_{DS} = 15\text{ V}, I_D = 20\text{ A}$	Ch-2		85		
<b>Dynamic<sup>a</sup></b>							
Input Capacitance	$C_{iss}$	Channel-1 $V_{DS} = 15\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	Ch-1		830	$\mu\text{F}$	
			Ch-2		1980		
Output Capacitance	$C_{oss}$	Channel-2 $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	Ch-1		185	$\mu\text{F}$	
			Ch-2		455		
Reverse Transfer Capacitance	$C_{rss}$	Channel-1 $V_{DS} = 10\text{ V}, V_{GS} = 0\text{ V}, f = 1\text{ MHz}$	Ch-1		80	$\mu\text{F}$	
			Ch-2		165		
Total Gate Charge	$Q_g$	$V_{DS} = 15\text{ V}, V_{GS} = 10\text{ V}, I_D = 15\text{ A}$	Ch-1		15.6	24	nC
		$V_{DS} = 15\text{ V}, V_{GS} = 10\text{ V}, I_D = 20\text{ A}$	Ch-2		36	54	
		Channel-1 $V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 15\text{ A}$	Ch-1		7.7	12	
			Ch-2		17	26	
Gate-Source Charge	$Q_{gs}$	Channel-2 $V_{DS} = 15\text{ V}, V_{GS} = 4.5\text{ V}, I_D = 20\text{ A}$	Ch-1		2.6		
			Ch-2		5.7		
Gate-Drain Charge	$Q_{gd}$		Ch-1		3		
			Ch-2		5		
Gate Resistance	$R_g$	$f = 1\text{ MHz}$	Ch-1	0.2	1	2	$\Omega$
			Ch-2	0.2	0.9	1.8	

## Notes:

- a. Guaranteed by design, not subject to production testing.  
b. Pulse test; pulse width  $\leq 300\text{ }\mu\text{s}$ , duty cycle  $\leq 2\%$ .



<b>SPECIFICATIONS</b> ( $T_J = 25\text{ }^\circ\text{C}$ , unless otherwise noted)							
Parameter	Symbol	Test Conditions	Min.	Typ.	Max.	Unit	
<b>Dynamic<sup>a</sup></b>							
Turn-On Delay Time	$t_{d(on)}$	Channel-1 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		10	20	ns
Rise Time	$t_r$		Ch-2		20	40	
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		15	30	
			Ch-2		15	30	
Fall Time	$t_f$	Channel-1 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		15	30	
			Ch-2		25	50	
Turn-On Delay Time	$t_{d(on)}$	Channel-2 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 4.5\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		7	15	
			Ch-2		10	20	
Rise Time	$t_r$	Channel-1 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		5	10	
			Ch-2		10	20	
Turn-Off Delay Time	$t_{d(off)}$	Channel-2 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		15	30	
			Ch-2		10	20	
Fall Time	$t_f$	Channel-1 $V_{DD} = 15\text{ V}$ , $R_L = 1.5\ \Omega$ $I_D \cong 10\text{ A}$ , $V_{GEN} = 10\text{ V}$ , $R_g = 1\ \Omega$	Ch-1		17	35	
			Ch-2		25	50	
<b>Drain-Source Body Diode Characteristics</b>							
Continuous Source-Drain Diode Current	$I_S$	$T_C = 25\text{ }^\circ\text{C}$	Ch-1			16	A
			Ch-2			35	
Pulse Diode Forward Current <sup>a</sup>	$I_{SM}$		Ch-1			70	
			Ch-2			100	
Body Diode Voltage	$V_{SD}$	$I_S = 10\text{ A}$ , $V_{GS} = 0\text{ V}$ $I_S = 2\text{ A}$ , $V_{GS} = 0\text{ V}$	Ch-1		0.8	1.2	V
			Ch-2		0.38	0.48	
Body Diode Reverse Recovery Time	$t_{rr}$	Channel-1 $I_F = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$  Channel-2 $I_F = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	Ch-1		15	30	ns
Body Diode Reverse Recovery Charge	$Q_{rr}$		Ch-2		20	40	
			Ch-1		6	12	nC
Ch-2			15	32			
Reverse Recovery Fall Time	$t_a$	Channel-1 $I_F = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$  Channel-2 $I_F = 10\text{ A}$ , $di/dt = 100\text{ A}/\mu\text{s}$ , $T_J = 25\text{ }^\circ\text{C}$	Ch-1		9		ns
Reverse Recovery Rise Time	$t_b$		Ch-2		10.5		
			Ch-1		6		
Ch-2			9.5				

Notes:

- a. Guaranteed by design, not subject to production testing.  
 b. Pulse test; pulse width  $\leq 300\ \mu\text{s}$ , duty cycle  $\leq 2\%$ .

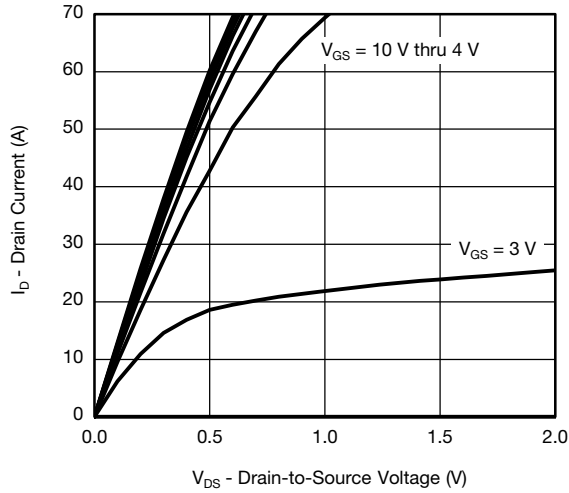
Stresses beyond those listed under "Absolute Maximum Ratings" may cause permanent damage to the device. These are stress ratings only, and functional operation of the device at these or any other conditions beyond those indicated in the operational sections of the specifications is not implied. Exposure to absolute maximum rating conditions for extended periods may affect device reliability.

# SiZ790DT

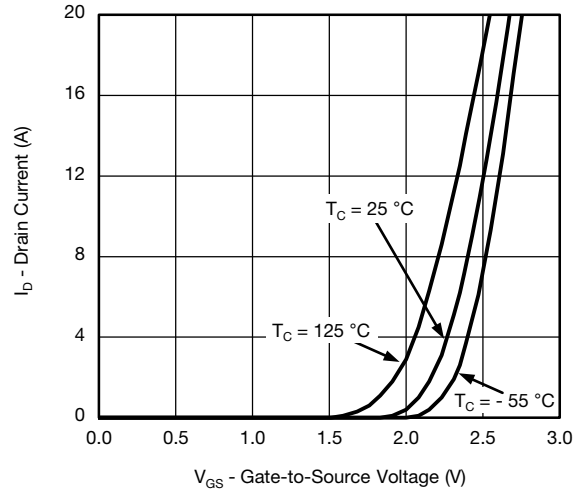
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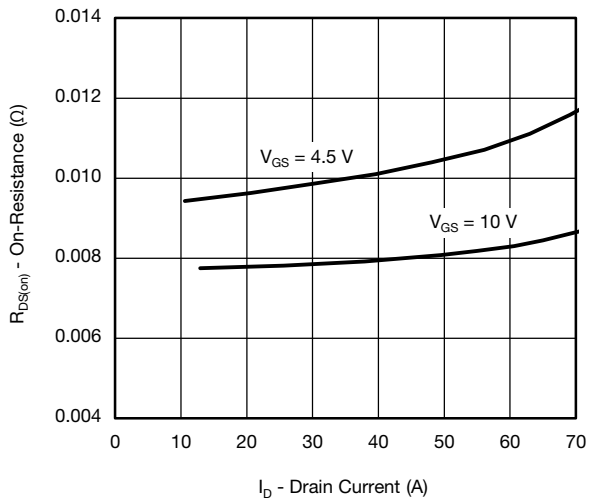
## CHANNEL-1 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)



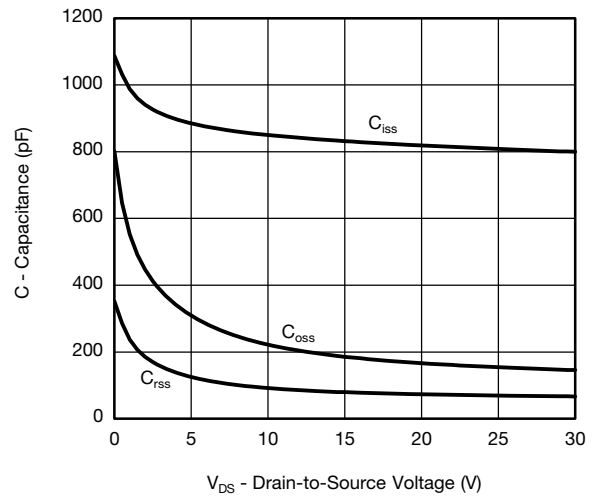
**Output Characteristics**



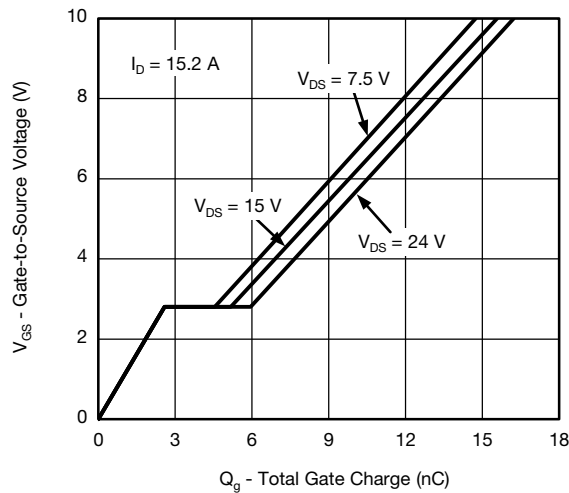
**Transfer Characteristics**



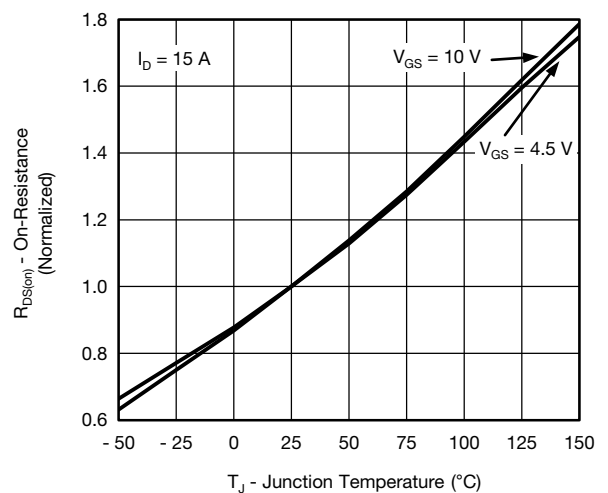
**On-Resistance vs. Drain Current**



**Capacitance**



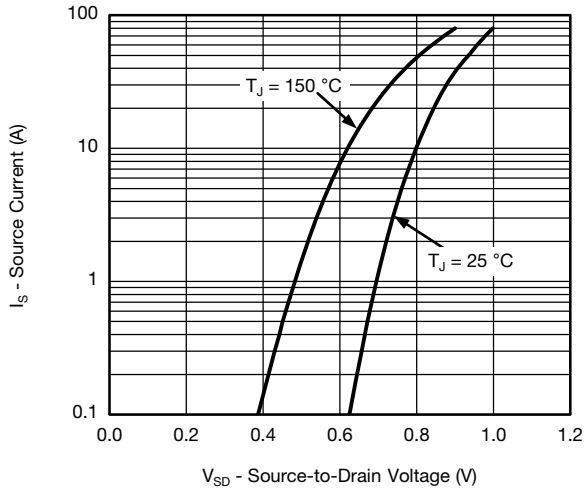
**Gate Charge**



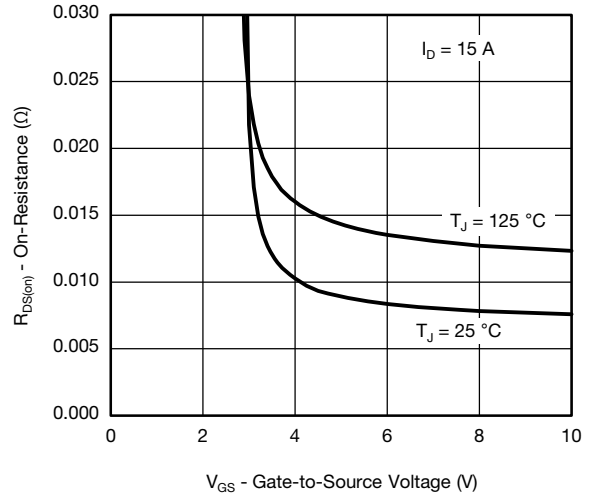
**On-Resistance vs. Junction Temperature**



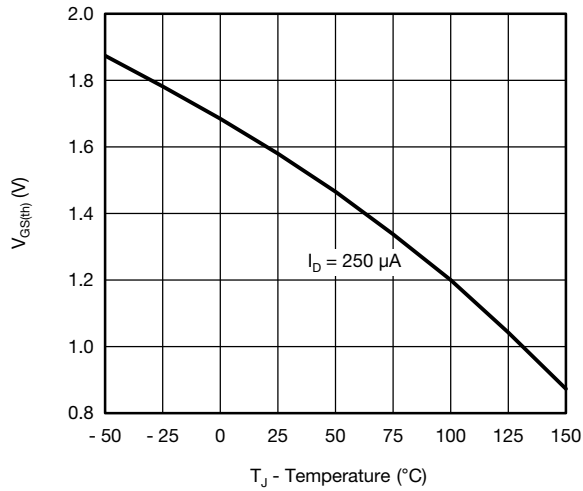
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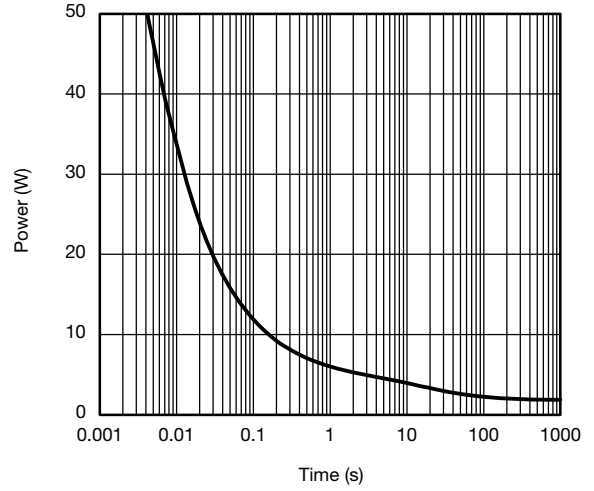
**Source-Drain Diode Forward Voltage**



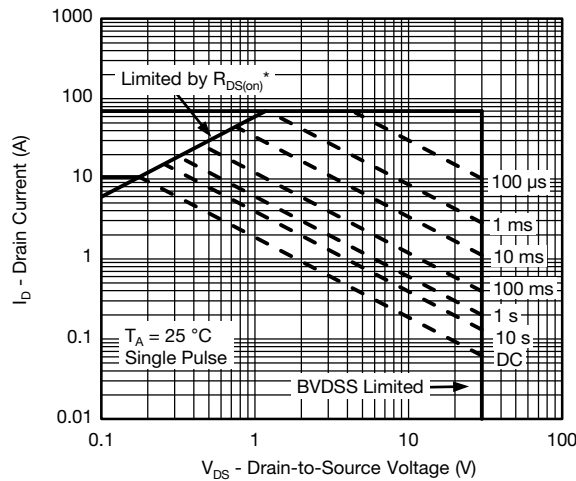
**On-Resistance vs. Gate-to-Source Voltage**



**Threshold Voltage**



**Single Pulse Power**



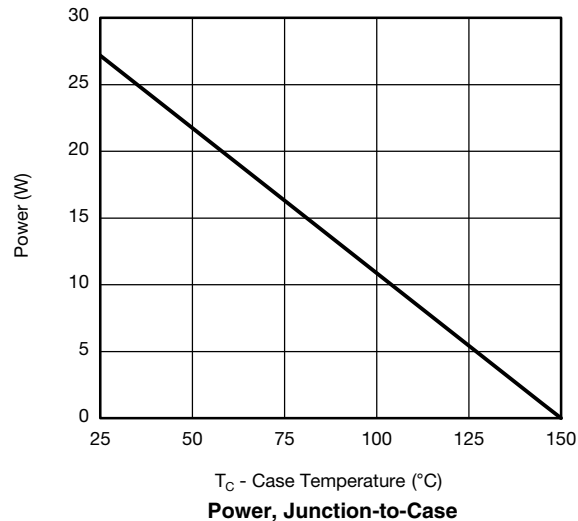
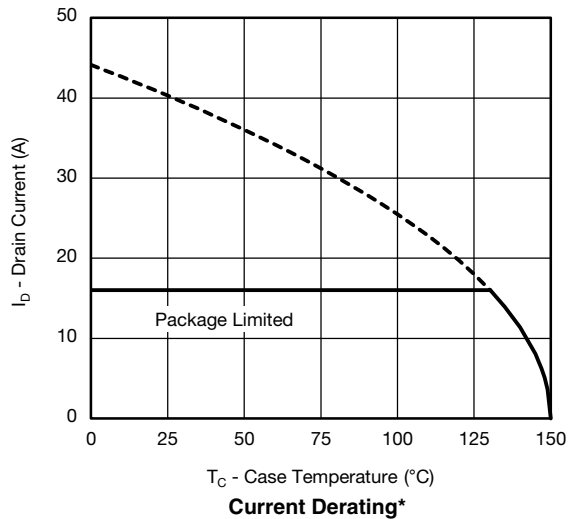
**Safe Operating Area, Junction-to-Ambient**

# SiZ790DT

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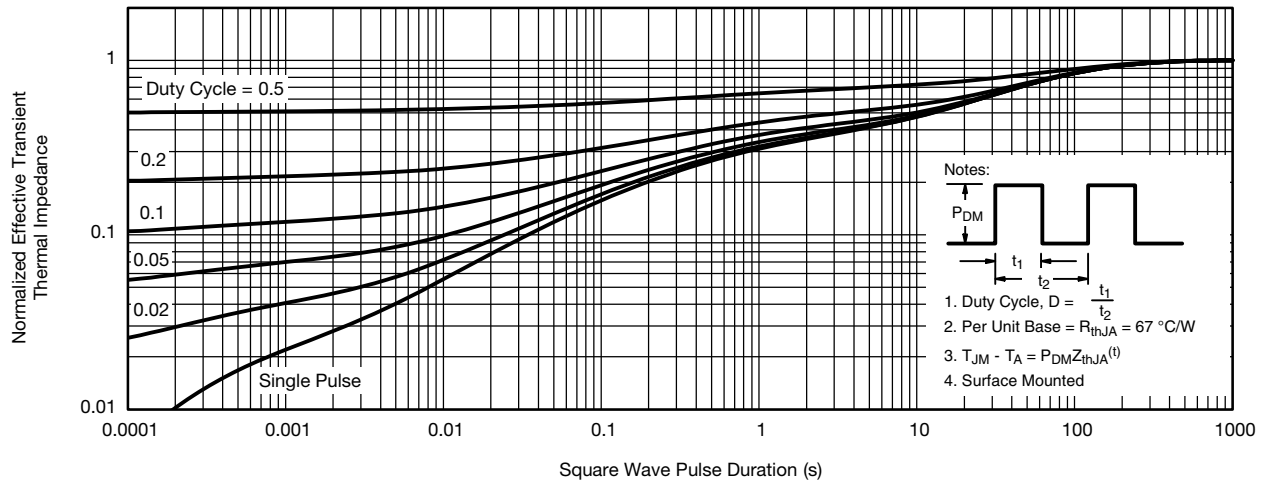
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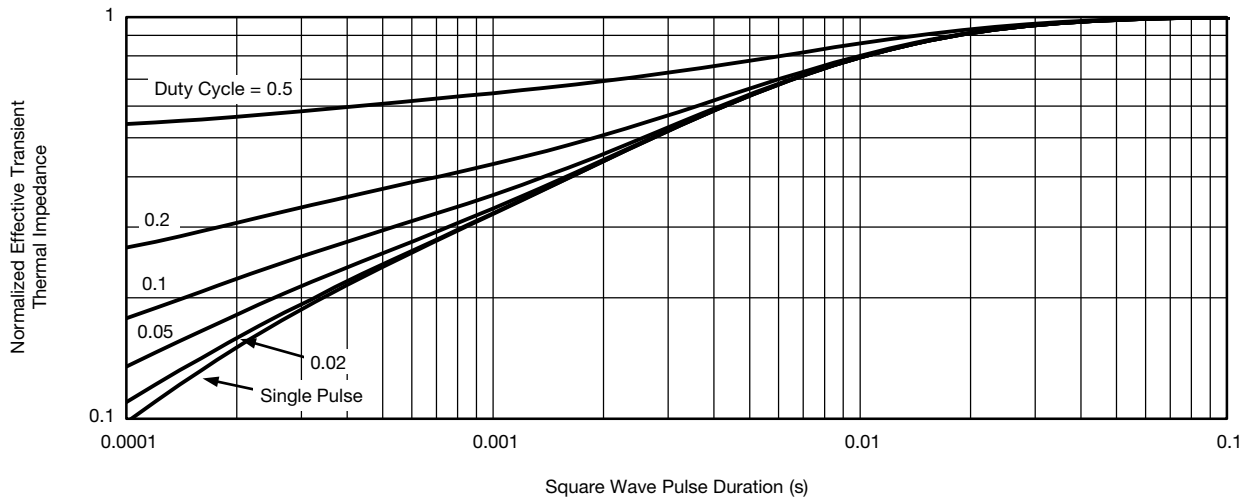
\* The power dissipation  $P_D$  is based on  $T_{J(max)} = 150$  °C, using junction-to-case thermal resistance, and is more useful in settling the upper dissipation limit for cases where additional heatsinking is used. It is used to determine the current rating, when this rating falls below the package limit.



**CHANNEL-1 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



**Normalized Thermal Transient Impedance, Junction-to-Ambient**



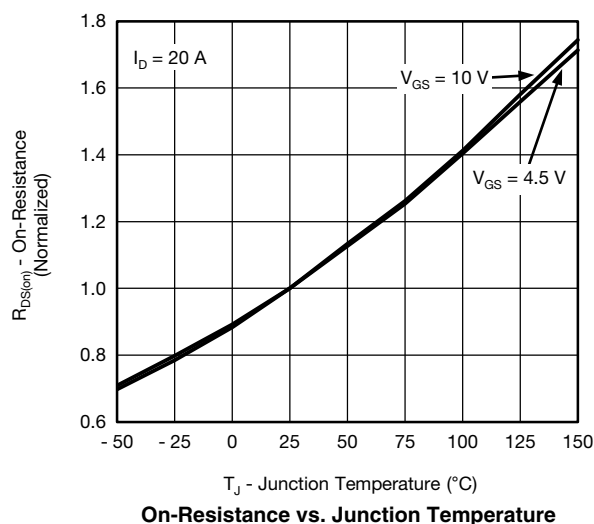
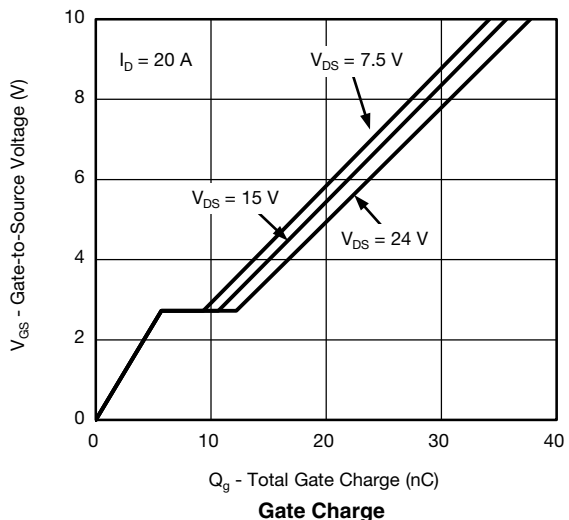
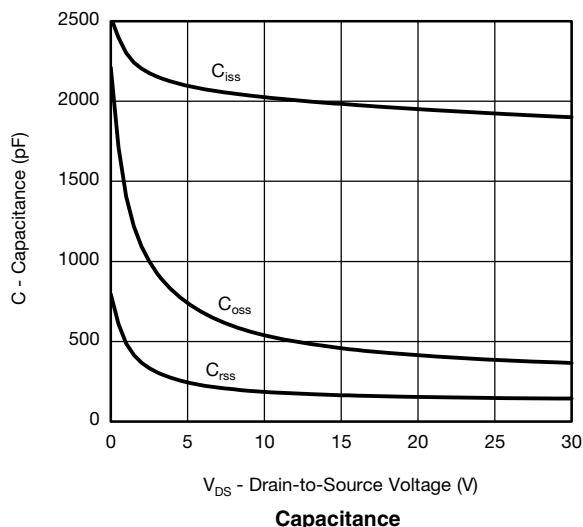
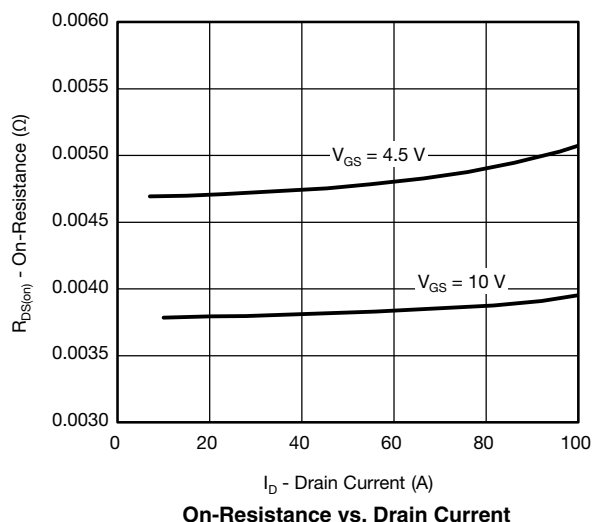
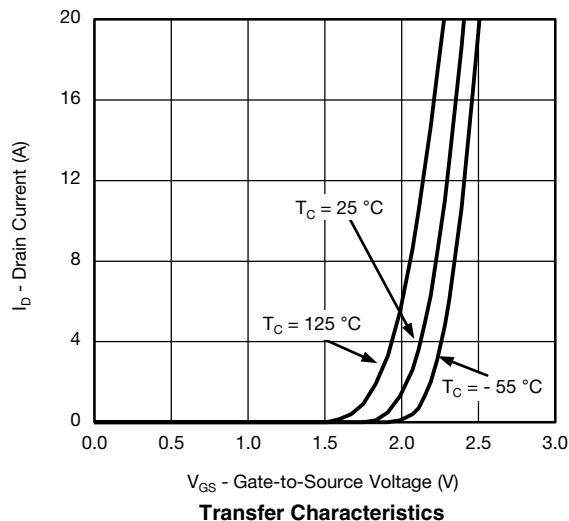
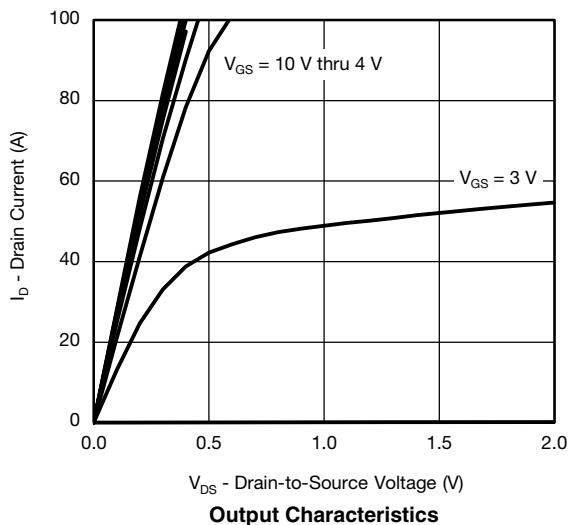
**Normalized Thermal Transient Impedance, Junction-to-Case**

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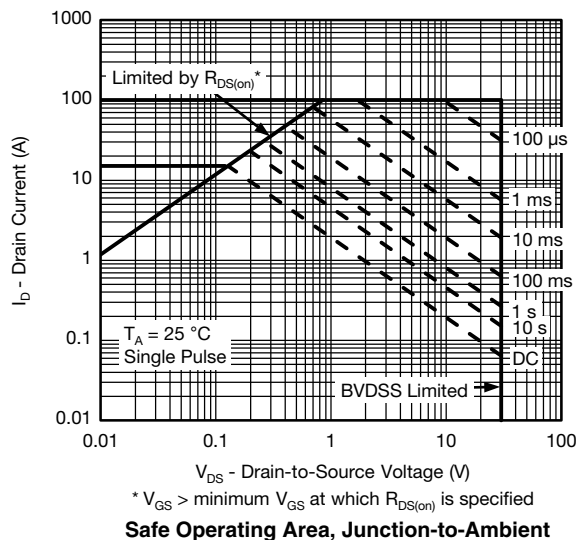
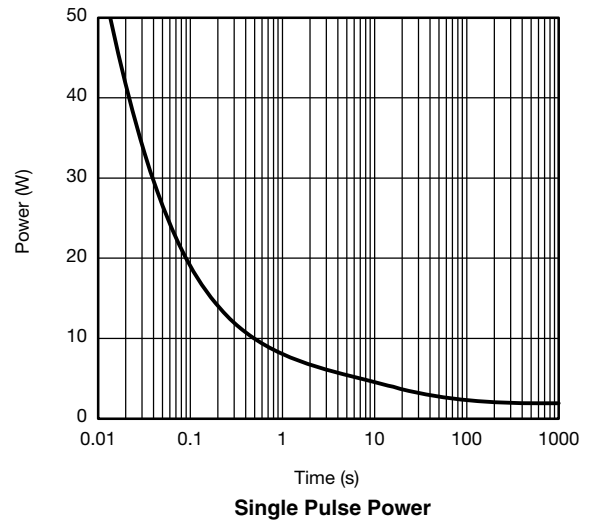
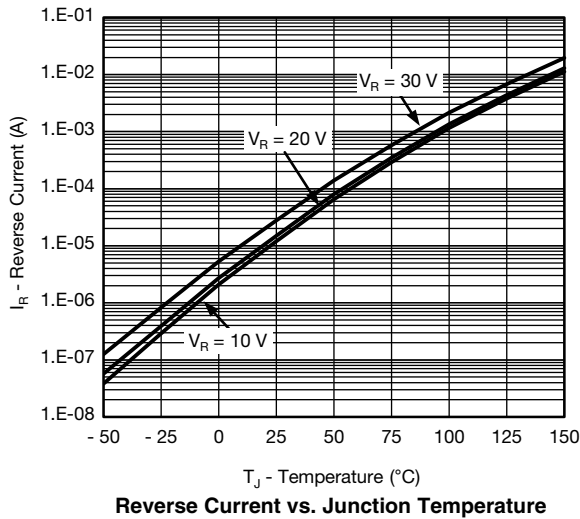
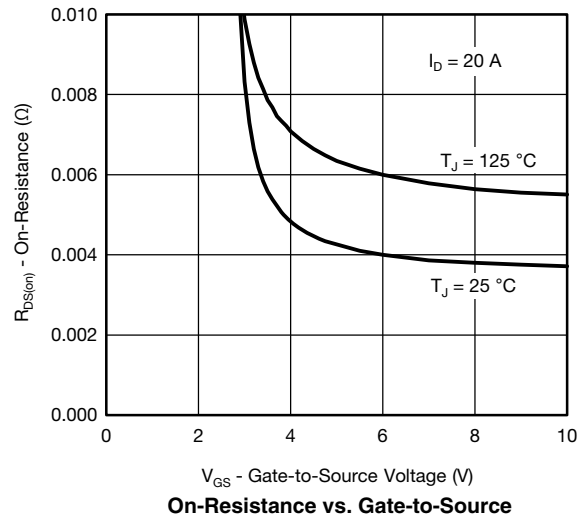
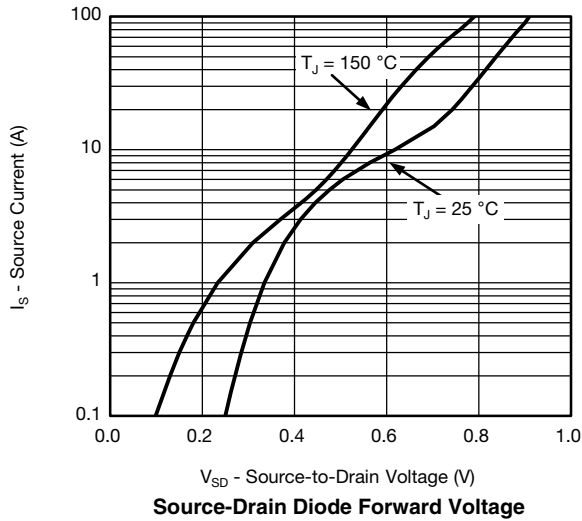
## CHANNEL-2 TYPICAL CHARACTERISTICS (25 °C, unless otherwise noted)







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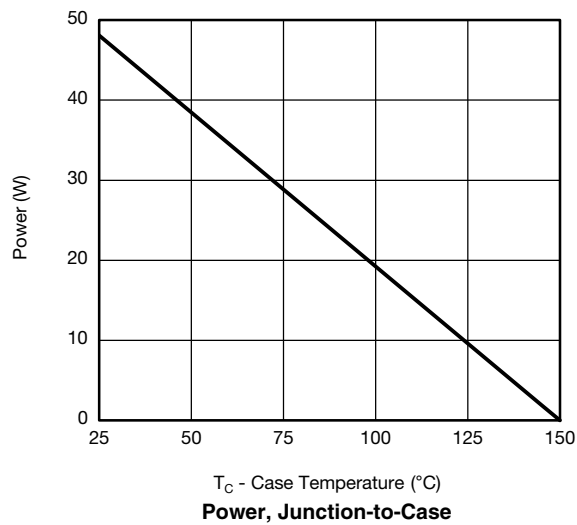
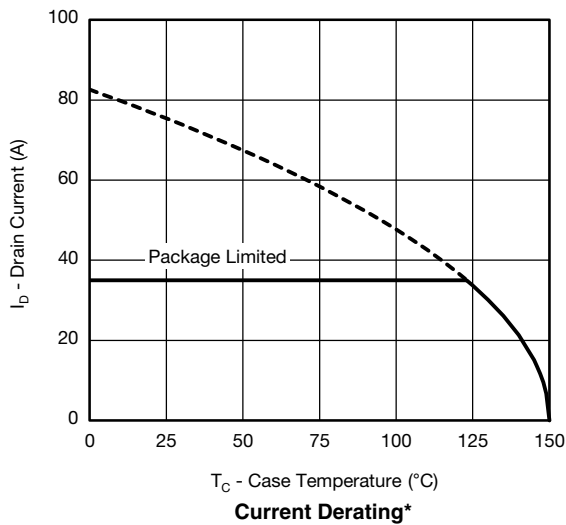


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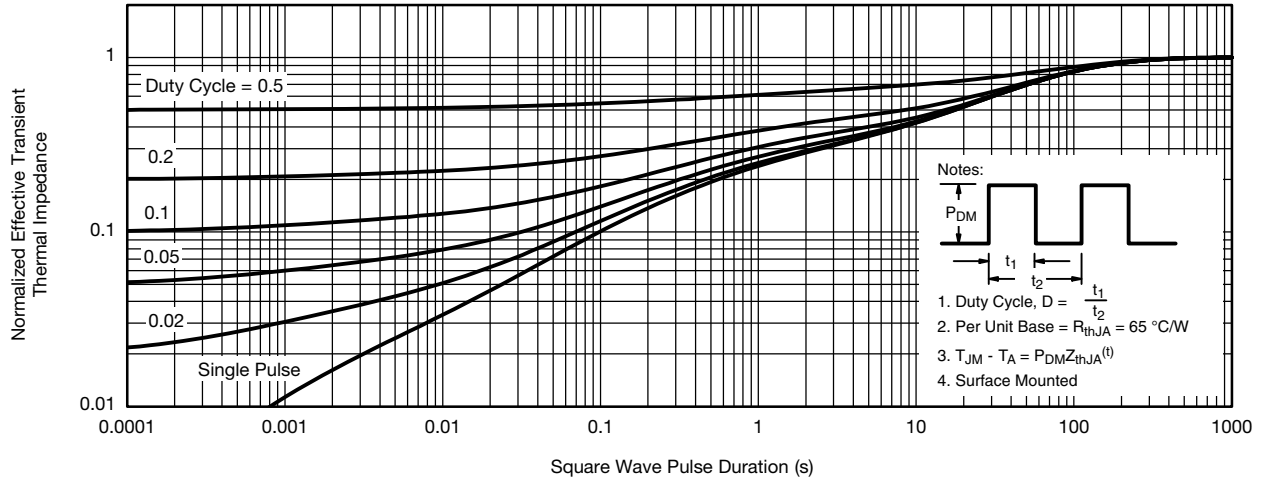
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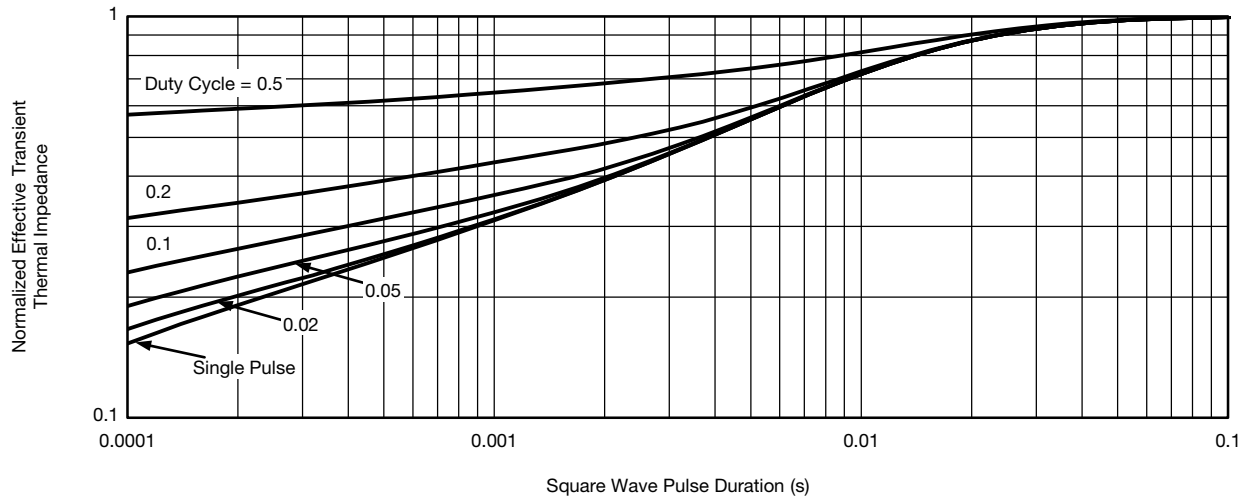
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**CHANNEL-2 TYPICAL CHARACTERISTICS** (25 °C, unless otherwise noted)



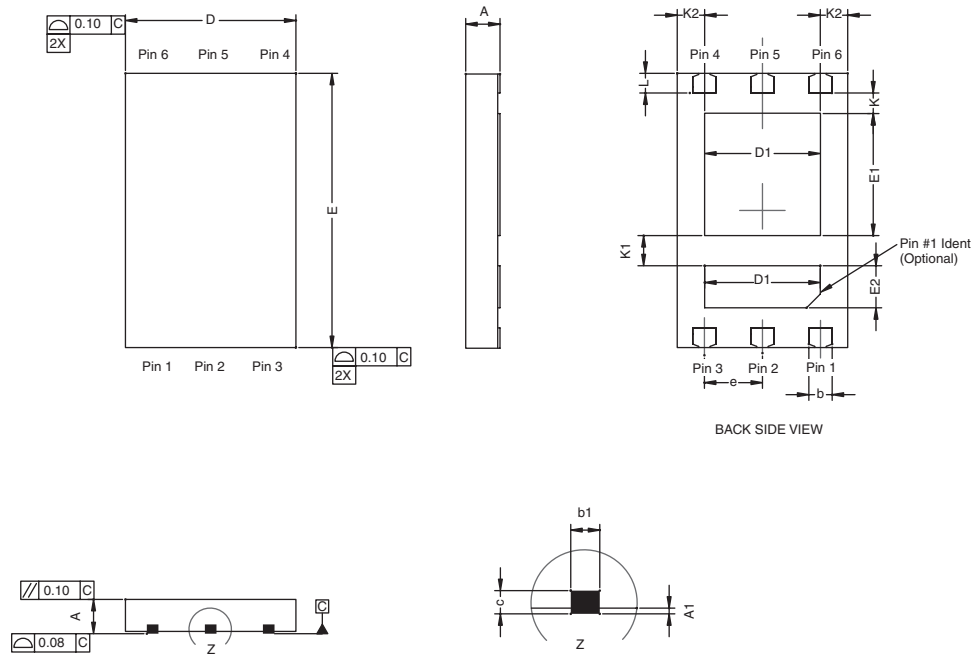
**Normalized Thermal Transient Impedance, Junction-to-Ambient**



**Normalized Thermal Transient Impedance, Junction-to-Case**

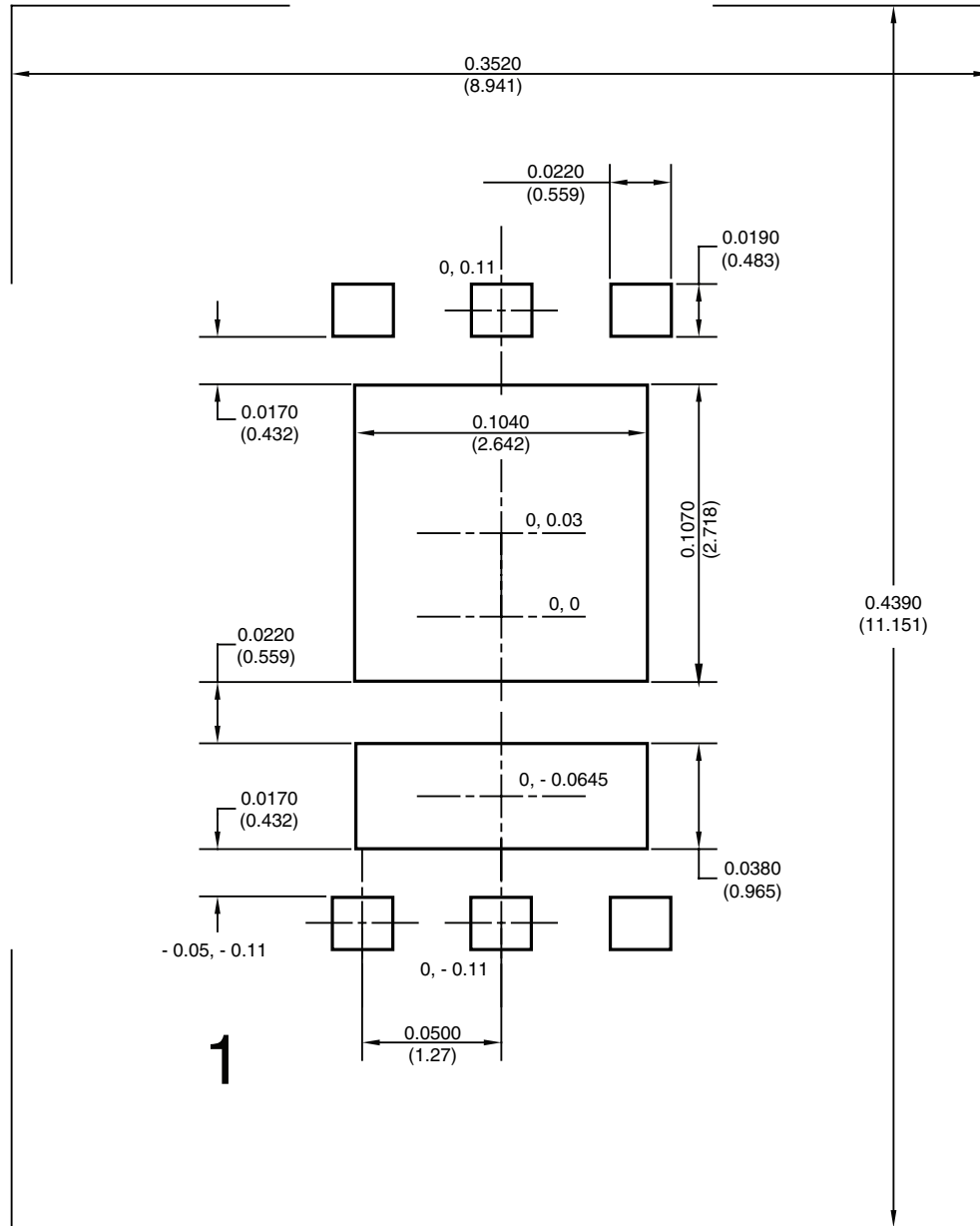
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### PowerPAIR™ 6 x 3.7 CASE OUTLINE



DIM.	MILLIMETERS			INCHES		
	MIN.	NOM.	MAX.	MIN.	NOM.	MAX.
A	0.70	0.75	0.80	0.028	0.030	0.032
A1	0.00	-	0.05	0.000	-	0.002
b	0.46	0.51	0.56	0.018	0.020	0.022
b1	0.20	0.25	0.38	0.008	0.010	0.015
C	0.18	0.20	0.23	0.007	0.008	0.009
D	3.65	3.73	3.81	0.144	0.147	0.150
D1	2.41	2.53	2.65	0.095	0.100	0.104
E	5.92	6.00	6.08	0.233	0.236	0.239
E1	2.62	2.67	2.72	0.103	0.105	0.107
E2	0.87	0.92	0.97	0.034	0.036	0.038
e	1.27 BSC			0.05 BSC		
K	0.45 TYP.			0.018 TYP.		
K1	0.66 TYP.			0.026 TYP.		
K2	0.60 TYP.			0.024 TYP.		
L	0.38	0.43	0.48	0.015	0.017	0.019
ECN: S-82772-Rev. B, 17-Nov-08 DWG: 5979						

## RECOMMENDED PAD FOR PowerPAIR™ 6 x 3.7



Recommended PAD for PowerPAIR 6 x 3.7  
 Dimensions in inches (mm)  
 Keep-out 0.3520 (8.94) x 0.4390 (11.151)



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